

HPF SERIES

(5.08 mm) .200"

POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn over

50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +105 °C

Voltage Rating:

850 VAC/1200 VDC

Insertion Depth:

(3.68 mm) .145" to (8.26 mm)

.325" (.368" (9.35 mm) plus board thickness minimum for bottom entry)

Wiping Distance:

(0.38 mm) .015"

Standard Creepage:

(2.82 mm) .111" (without -LC)

(1.38 mm) .054" (with -LC)

Standard Clearance:

(2.5 mm) .098" (without -LC)

(1.05 mm) .041" (with -LC)

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.15 mm) .006" max (02-10)*

(0.20 mm) .008" max (11-20)*

*(.004" stencil solution may be available; contact IPG@samtec.com)

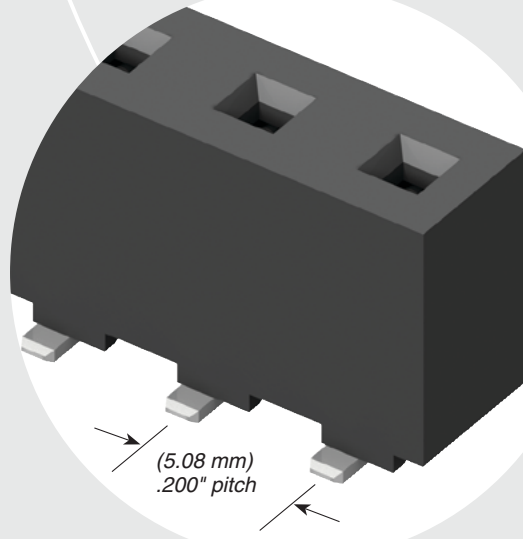
RoHS Compliant:

Yes

Mates with:

HPM, HPW

HPF/HPM	
PINS	CURRENT RATING (PER CONTACT)
1	16.6 A
2	14.4 A
3	13.2 A
4	12.7 A
20	8.9 A



Surface Mount or Through-hole

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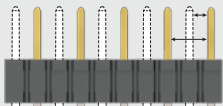
- Three-finger Power Eye contact
- Locking clip option

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



CREEPAGE AND CLEARANCE



Selectively loading contacts achieves customer specific creepage and clearance requirements. Contact asp@samtec.com

Note: Some lengths, styles and options are non-standard, non-returnable.

HPF — **NO. PINS PER ROW** — **LEAD STYLE** — **PLATING OPTION** — **S** — **OTHER OPTIONS**

02 thru 20

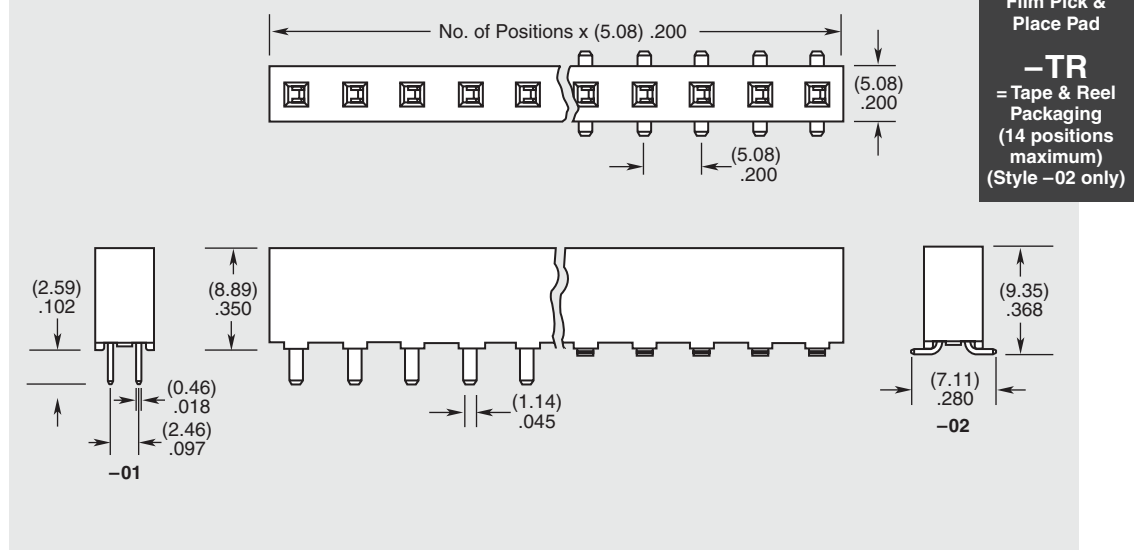
-01 = Through-hole
-02 = Surface Mount

-T = Matte Tin

-LC = Locking Clip (Manual placement required) (Style -02 only)

-K = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging (14 positions maximum) (Style -02 only)



Due to technical progress, all designs, specifications and components are subject to change without notice.